

IBM xSeries Technology

Scale-up / Scale-out *High-End offering*



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Agenda

- IBM Offering Scale-Up / Scale-Out positioning
- Detailed answer to yesterday's question
- IBM Initiative: EXA Architecture Scale-up
- Products: x260 / x366 / x460
- X3 Chipset details
- Intel Xeon vs AMD Opteron: fundamental differences





Thriving in the unpredictable e-business market requires a robust and adaptable IT infrastructure, designed for your business.

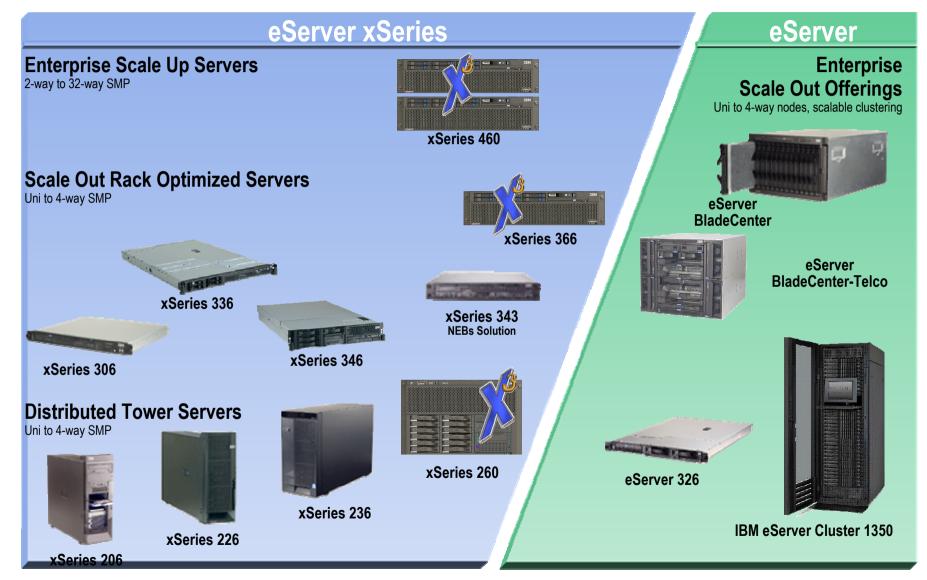
No other company in the world offers the enterprise expertise applied to such a breadth of product as IBM eServer.



IBM Offering - Scale-Up / Scale-Out positioning

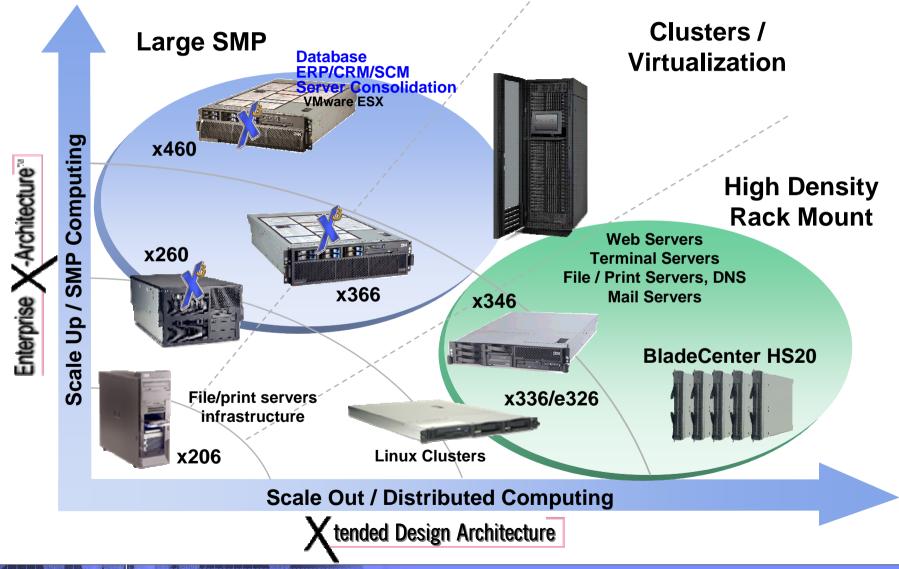


IBM eServer Industry-Standard Portfolio





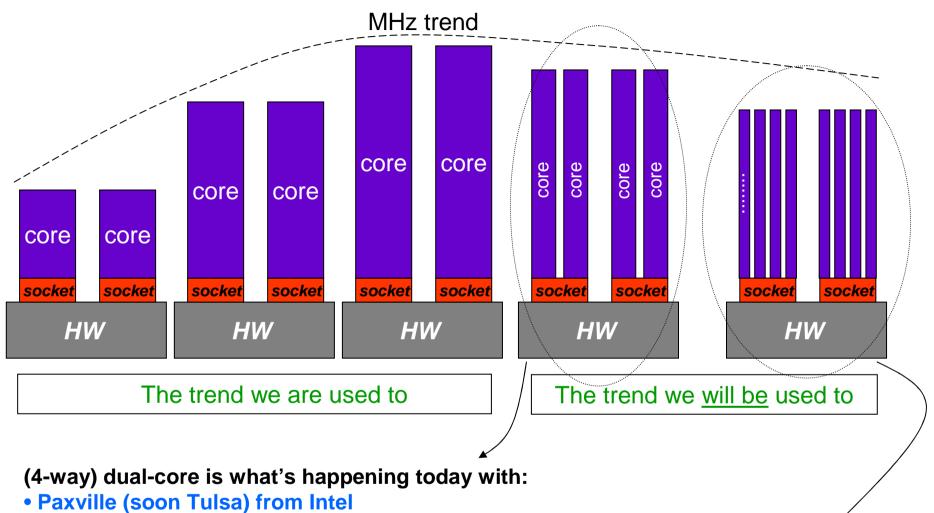
Advancing X-Architecture





Detailed answer to yesterday's question

Dual Core and Multi Core ?



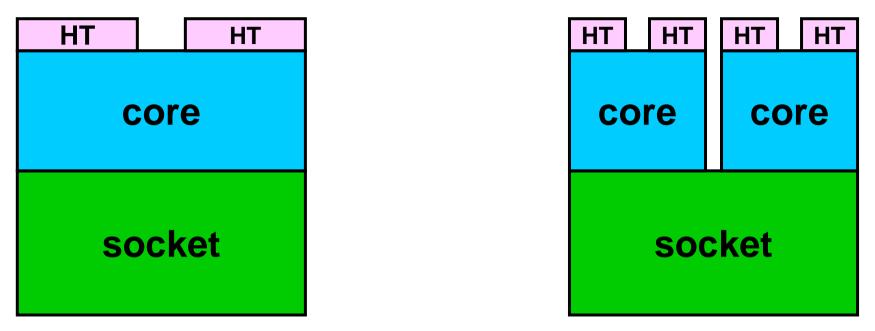
Opteron from AMD

(4-way) quad-core is what will happen in 2007(?) with:

- Tigerton (used to be Whitefield) from Intel
- Opteron (same current micro-architecture) from AMD

Power (and cooling) are becoming THE challenge and priority #1 from now on !

Dual core and HyperThreading ?



- HT builds on top of the core whether it is single or dual !

- HT and dual core has no correlation with each other (for example Opterons are dual core but do not have any HT concept/technology)

-Two HT logical CPU's share much more things of a core than what two cores share on a socket

	Architectural state	Execution resources	On-board caches	System Bus Interface
"Legacy" CPU	exclusive	exclusive	exclusive	exclusive
"HyperThreaded" CPU	exclusive (shared	shared	shared
Dual/Multi Core CPU	exclusive (exclusive	exclusive/shared	shared



IBM Initiative: EXA Architecture – Scale-up



IBM defines High-end Industry-Standard Servers

1st Generation: 2001

- x360: 6-month time to market advantage, Most rack dense 4w (3U) ever introduced
- x440: 12-month TTM, Most rack dense 8w (4U), Most successfully benchmarked server in history (35 #1's)
- XpandOnDemand Scalability up to 16-way plus Remote I/O
- Industry-first High Availability Technologies: Active Memory & Memory ProteXion
- Leadership Virtualization for Server Consolidation

2nd Generation: 2003

- x365: Leadership density (3U) with 4X storage capacity & advanced EXA features
- x445: the fastest industrystandard server in history, 20 more #1 benchmarks (little competition to compare)
- x455: Unleashing EXA on Itanium2 for pure 64-bit
- XpandOnDemand Scalability up to 32-way plus Remote I/O
- 10 Consecutive Quarters (3Q02) as #1 8-way database server in the Industry

3rd Generation: 2005

- x366: Leadership 4-socket performance, First-to-market with 64-bit Xeon MP
- x460: xSeries 32-way flagship optimized for scalability & virtualization with 100%+ higher performance
- x260: Extending EXA to the 4-way Tower space with maximum storage for SMB
- 64-bit Extensions for higher performance, application flexibility (32-bit & 64-bit) and investment protection



Products: x260 / x366 / x460

High-Performance xSeries Positioning



x260: 4-way Tower Target: SMB, Remote/ Branch Office

Apps: SMB, Collaboration, Departmental database

eServer X3: 3rd Gen EXA 64-bit Intel Xeon MP Competitive Price-perf Latest technology *SAS, PCI-X2, DDR2* High Availability 7U Tower or Rack Maximum Int. Storage Tape Backup Support Dual-core Capable



x366: 4-way Rack Target: Enterprise & Midmarket

Apps: Collaboration, Database, ERP, SCON

eServer X3: 3rd Gen EXA 64-bit Intel Xeon MP Leadership 4-way perf **38% better than x365** Latest technology *SAS, PCI-X2, DDR2* High Availability 3U Rack-optimized Maximum Int. Storage Dual-core Capable



x460: 4-way+ Rack Target: Enterprise & Mid-market **Database** MS SQL, DB2, Oracle ERP/CRM/SCM SAP, Siebel, i2 Server Consolidation VMware ESX Server X3: 3rd Gen EXA 64-bit Intel Xeon MP Leadership 8-way perf 50% better than x445 Leadership 16-way+ perf 80% better than x445 Latest technology SAS, PCI-X2, DDR2 **High Availability** XpandOnDemand to 32way **Dual-core** Capable





ServerWorks GC-HE Chipset

- 1-way to 4-way, 32-bit with 400MHz FSB
- Intel Xeon MP: 2.0/1M, 2.2/2M, 2.7/2M, 3.0/4M
- 12 DIMMs Total: All standard
- 24GB Max Memory (12 x 2GB DIMM)
- PC1600 DDR SDRAM, 2-way Interleaving
- Ultra160 SCSI, Optional RAID
- Max Storage = 12 HDDs x 146 GB = 1.7TB
- Active PCI-X: 6 slots @ 100MHz
- Broadcom 5703 Single Port Gigabit Ethernet
- Chipkill + Active Memory: Online Spare
- 4 x 370W Hot-swap Power Supplies, N+N, 110V/220V
- Remote Supervisor Adapter 2 Optional
- 3-year Next Business Day 9x5 Warranty

YV-xSeries

7U Rack or Tower with Internal Tape Support



- XA-64e 3rd Generation Chipset
- 1-way to 4-way SMP, Dual-core Capable
- Intel Xeon MP: 3.16/1M, 3.66/1M, 667MHz FSB
- 16 DIMMs Total: 4 Standard, 12 Optional
- 64GB Max Memory (16 x 4GB DIMM)
- DDR2 SDRAM PC2-3200, 2-way Interleaving
- Adaptec Serial Attached SCSI (SAS), Int. RAID5
- Max Storage = 12 3.5" HDDs x 300 GB = 3.6TB
- Active PCI-X 2.0: 6 slots @ 266MHz
- Broadcom 5704 Dual Port Gigabit Ethernet
- Chipkill + Memory ProteXion + Memory Mirroring
- 4 x 775W Hot-swap Power Supplies, N+N, 110V/220V
- Remote Supervisor Adapter 2 Slimline optional
- 3-year Next Business Day 9x5 Warranty
- 7U Rack or Tower with Internal Tape Support







- 1-way to 4-way, 32-bit with 400 MHz FSB
- Intel Xeon MP: 2.0/1M, 2.2/2M, 2.7/2M, 3.0/4M
- 16 DIMMs Total: 8 Standard, 8 Optional
- 32GB Max Memory (16 x 2GB DIMM)
- PC2100 DDR SDRAM, 2-way Interleaving
- LSI 53C1030 Ultra320 SCSI, Integrated RAID-1
- Max Storage = 6 HDDs x 146 GB = 876 GB
- Active PCI-X: 4@133MHz, 1@100MHz, 1@33MHz
- Remote I/O + RIO Sharing between x365's
- 24X CD-ROM
- Broadcom 5704 Dual Port Gigabit Ethernet
- Chipkill + Memory ProteXion + Memory Mirroring
- 2 x 950W Hot-swap Power Supplies, N+N, 110V/220V
- Remote Supervisor Adapter 2 Standard

YV-xSeries

- 1-year or 3-year Next Business Day 9x5 Warranty
- 3U: 17.46"(444mm) x 5.07"(129mm) x 28.1"(715mm)

x366



- XA-64e 3rd Generation Chipset
- 1-way to 4-way SMP, Dual-core Capable
- Dual-bus x86-64 Architecture, 667MHz FSB
- Intel Xeon MP: 3.16/1M, 3.66/1M
- 16 DIMMs Total: 4 Standard, 12 Optional
- 64GB Max Memory (16 x 4GB DIMM)
- DDR2 SDRAM PC2-3200, 2-way Interleaving
- Adaptec Serial Attached SCSI (SAS), opt. RAID5
- Max Storage = 6 2.5" HDDs x 73 GB = 438 GB
- Active PCI-X 2.0: 6 slots @ 266MHz, No Remote I/O
- 8X DVD-ROM
- Broadcom 5704 Dual Port Gigabit Ethernet
- Chipkill + Memory ProteXion + Memory Mirroring
- 2 x 1300W Hot-swap Power Supplies, N+N, 220V
- Remote Supervisor Adapter 2 Slimline opt.
- 3-year Next Business Day 9x5 Warranty
- **3U: 17.46"(444mm) x 5.07"(129mm) x 28.1"(715mm)**

x445



- XA-32 2nd Generation Chipset
- 2-way to 32-way SMP, 32-bit with 400MHz FSB
- Intel Xeon MP: 2.0/1M, 2.2/2M, 2.7/2M, 3.0/4M
- Intel Xeon DP 3.0GHz up to 4-way
- 64MB XceL4 per CEC, 512MB Max
- 64GB max addressable memory supported
- DDR SDRAM PC2100, 2-way Interleaving
- LSI Ultra320 SCSI, Integrated RAID-1
- Max Storage = 2 HDDs x 146 GB = 292 GB
- Active PCI-X: 2@133MHz, 2@100MHz, 2@66MHz
- Remote I/O + RIO Sharing
- 2 x 1200 Watt Power Supplies, Hot-swappable
- Broadcom 5704 dual port GbE
- Remote Supervisor Adapter II for EXA (std)
- Active Memory + Hot-swap and Hot-add Memory
- 3-year Next Business Day 9x5 Warranty
- 4U: 19"(483mm) x 7"(178mm) x 28.1"(714mm)
- 20 #1 Benchmarks...and counting!!!



- **x460**
- XA-64e 3rd Generation chipset
- 2-way to 32-way SMP, Dual-core Capable
- Dual-bus x86-64 Architecture, 667MHz FSB
- Intel Xeon MP: 2.83/4M, 3.16/8M, 3.33/8M
- 256MB XceL4v per chassis, 2GB Max
- 64GB Max Memory per chassis, 512GB Max Total
- DDR2 SDRAM PC2-3200, 2-way Interleaving
- Adaptec Serial Attached SCSI (SAS), Opt. RAID5i
- Max Storage = 6 2.5" HDDs x 73 GB = 438 GB
- Active PCI-X 2.0: 6 available slots, all 266MHz
- MXE-460 Modular Xpansion Enclosure (>4-way)
- **2 x 1300 Watt Power Supplies, Hot-swappable**
- Broadcom 5704 dual port GbE
- Remote Supervisor Adapter II Slimline (std)
- Active Memory + Hot-swap (All DIMMs accessible)
- 3-year Next Business Day 9x5 Warranty
- **3U: 19"(483mm) x 5.25"(133mm) x 27.5"(698mm)**
- Up to 125% performance improvement over x445

Changes in Red

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x460 & MXE Supported Configurations

XpandOnDemand[™] Scalability

Modular Building-block Scalability eliminates the need for fork-life upgrades and provides an easier growth path to larger, scale-up high-performance SMP configurations

Perfect for:



x460 2w-4w Single Chassis Up to 64GB Memory

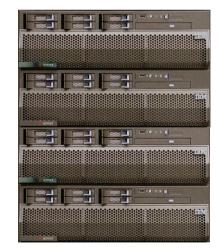


YV-xSeries

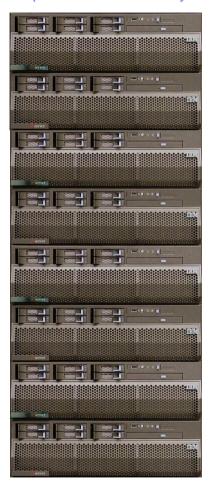
x460 + (1) MXE-460 Two Chassis 8-way Up to 128GB Memory



x460 + (3) MXE-460 Four Chassis 16-way Up to 256GB Memory



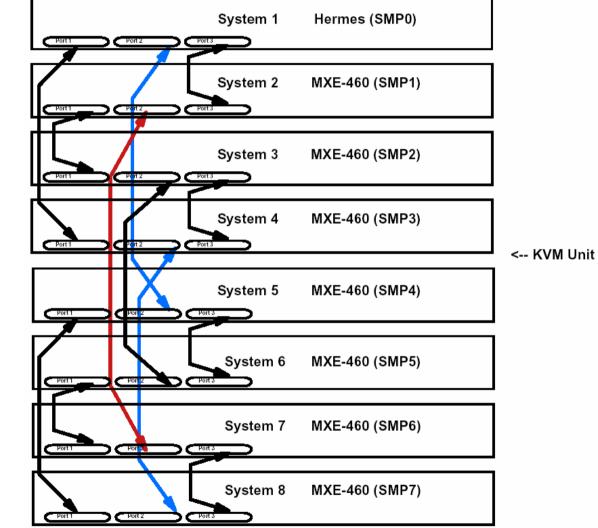
x460 + (7) MXE-460 Eight Chassis 32-way Up to 512GB Memory





x460 32-way Cabling Diagram

- All 8-way and 16-way Configurations only require the 2.3m cable
- Only the 32-way requires the 2.9m cable
 - Red & blue cables: 2.9m
 - Black cables: 2.3m
- This cable diagram applies to both MXE and partitioning with the x460





IBM X3 Chipset details

eServer X3: Third-generation Enterprise X-Architecture

Mainframe-inspired innovation that delivers break-through performance, mission-critical availability, and unmatched modular scalability to become *the leading 64-bit solution architecture for commercial enterprise applications*, virtualization, and web services.

Performance

#1 x86 4w, 8w, 16w, 32w Performant
32-bit/64-bit x86 compatibility
Reduced latencies of 3G Chipset
XceL4v[™] Server Accelerator Cache
PCI-X2, SAS, DDR2 Memory
Optimized for Windows & Linux and the application-serving tier



High Availability

•64GB Active Memory

- •OS-independent Mirroring
- •Chipkill & Mem ProteXion
- •Hot-swap & Hot-add in all major subsystems

•Reliability of Intel Xeon MP Front-side bus architecture



IBM

Scalability

Improved pay-as-you-grow with more granularity in CPU, I/O, RAM
2-32-sockets, Up to 512GB Memory, Dual-core Capable
Flexibility with MXE scalability or x460 partitioning
Optimized for Windows & Linux and the database-serving tier



Manageability

- Integrated hardware & remote mgmt software
- •Integrated hardwarebased security (TPM)
- •Comprehensive alerting with PFA and Light Path Diagnostics
- •Multi-chassis partitioning



Director

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Enterprise X-Architecture Chipset Changes

XA-32 1st generation 2002: x360, x440

Memory Controller: Cyclone Jr. 2.2 –Memory Mirroring

Processor Controller: Twister 2.1.1 -32MB XceL4

PCI Bridge I/O Controller: • Winnipeg 4 Ceramic –Remote I/O Support

XA-32 2nd generation 2003: x365, x445

Memory Controller: Cyclone 3 –Hot-swap memory –40% more aggregate I/O

Processor Controller: Twister 3 -12% lower latency -64MB XceL4

PCI Bridge I/O Controller: • Winnipeg 4 Plastic -\$50 cost savings XA-64e 3rd generation

2005: x366, x460, x260

Integrated Processor & Memory Controller:

Hurricane

-Dual-bus architecture -Support for EM64T •x86 64-bit Extensions -256MB XceL4v Cache •Virtual L4 Cache

PCI Bridge I/O Controller: Calgary –PCI-X 2.0 Support –All slots 266MHz

-Used by x, i, p, zSeries





Normalized for CPUs, the EXA 3G chipset represents a 25% to 40% performance improvement over 2nd Generation



X3: Leadership Technology – Memory

Memory ProteXion[™] - Redundant Bit Steering

- Redundant Bit Steering is similar to the "hot-spare" of a DASD Array
- Utilizes unused bits in each memory DIMM (hot spare bits)
- Double the number of Chipkills sustainable per server
- Included at no additional cost, requires no additional hardware, and works independently of operating system

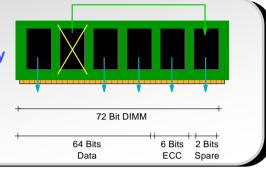
Memory Mirroring

- Propels Intel-based servers towards continuous operations
- Dramatically increases uptime and allows scheduled maintenance
- Mainframe capability and reliability
- Operating System Independent: Does not require drivers or OS Support
- First introduced on the x440 and x445

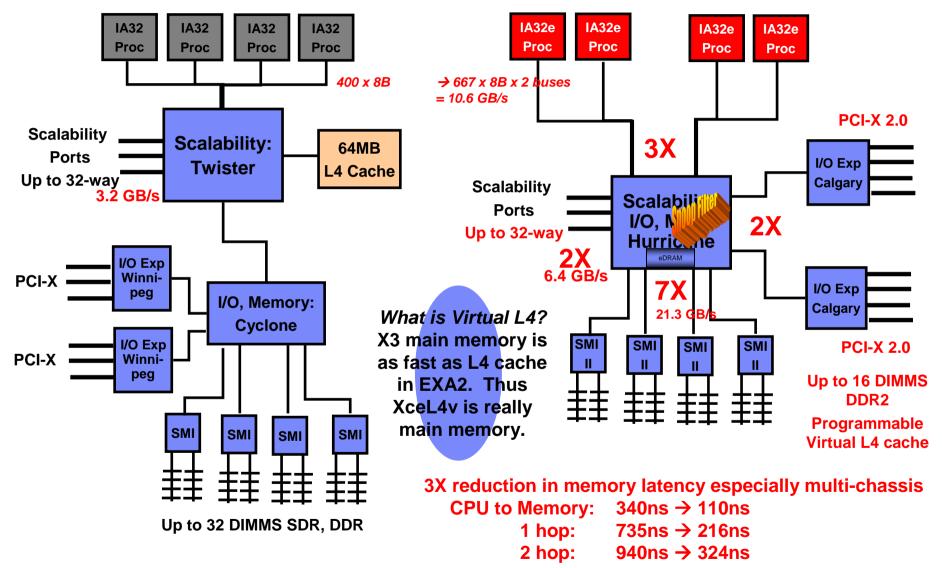
Chipkill™ Memory

- Integrated into XA-32 and XA-64 chipsets for using off-the-shelf DIMMs
- Better memory reliability to support In-Memory Databases
- Chipkill Memory enables increased availability by detecting and
- Correcting multiple-bit memory DIMM errors
- Third-Generation Chipkill design (1: 7000 M10, 2: 7600/6000)



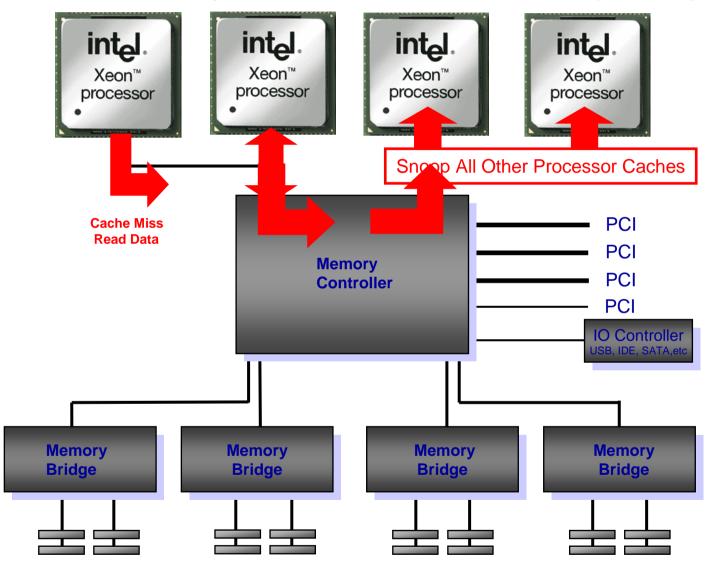


EXA2 vs. EXA3: Fatter pipes & lower latencies



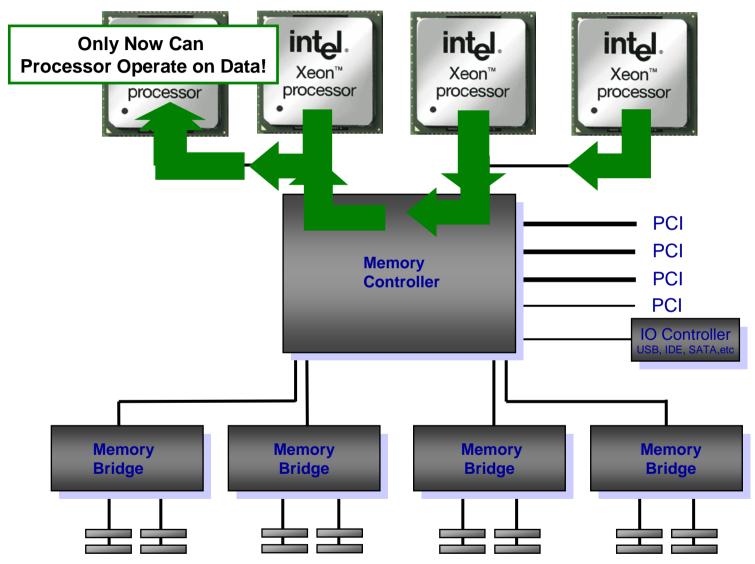
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Xeon Coherency Protocol – CPU Snoop Request



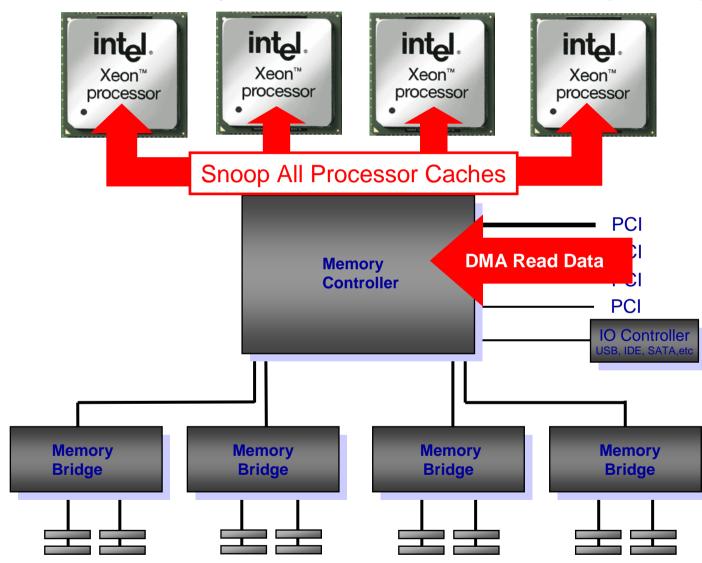
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Xeon Coherency Protocol – CPU Snoop Response



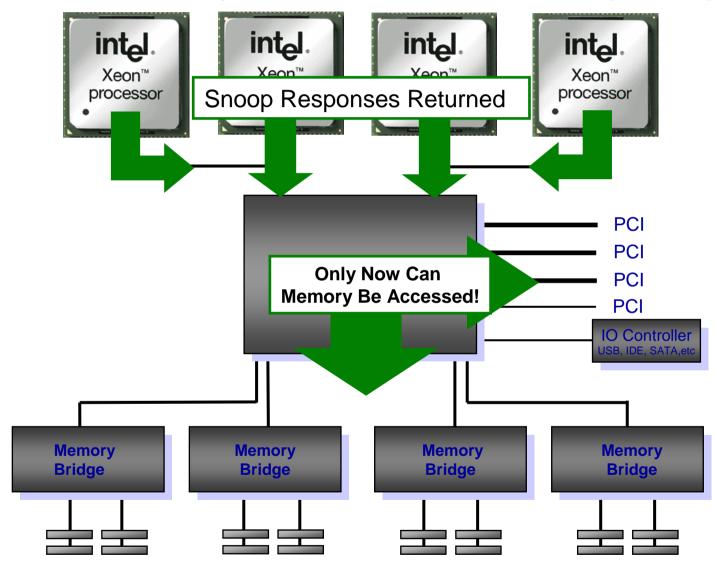
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Xeon Coherency Protocol – DMA Snoop Request



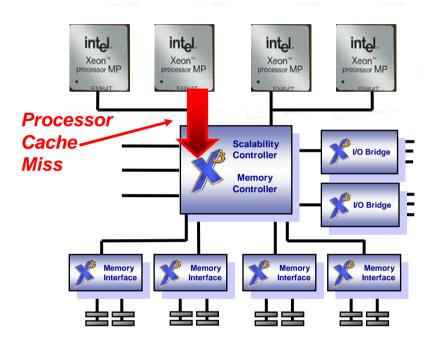
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Xeon Coherency Protocol – DMA Snoop Response





Chipset – Snoop Filter Cache Miss – Snoop Filter Miss Example

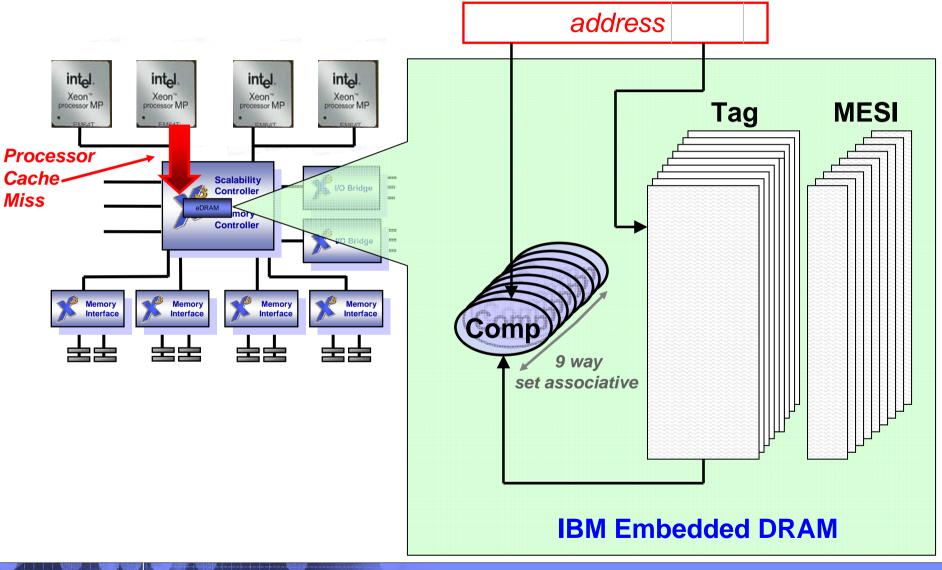




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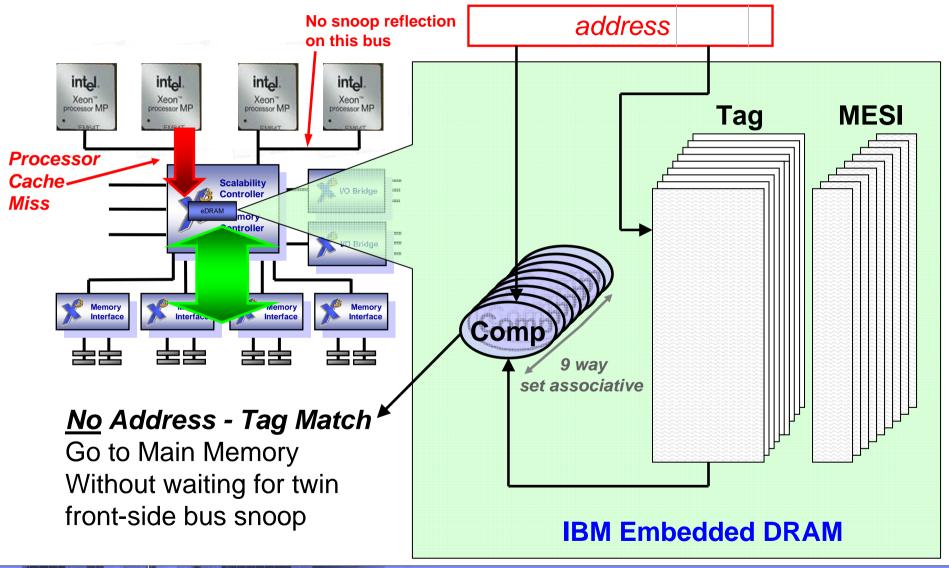


Chipset – Snoop Filter Cache Miss – Snoop Filter Miss Example



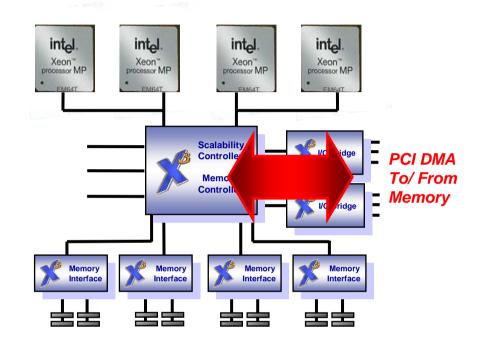


Chipset – Snoop Filter Cache Miss – Snoop Filter Miss Example

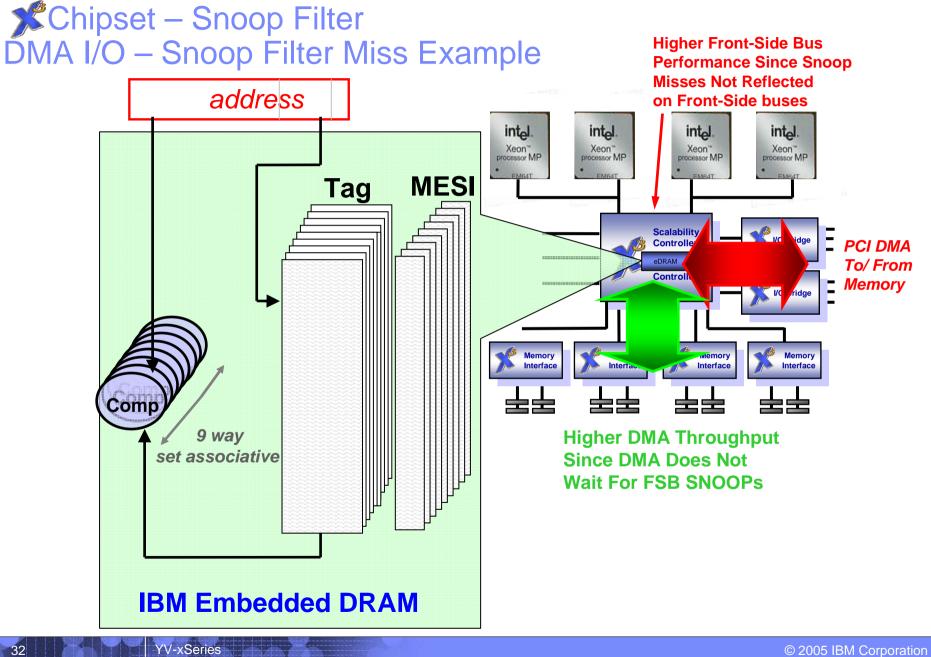




Chipset – Snoop Filter DMA I/O – Snoop Filter Miss Example







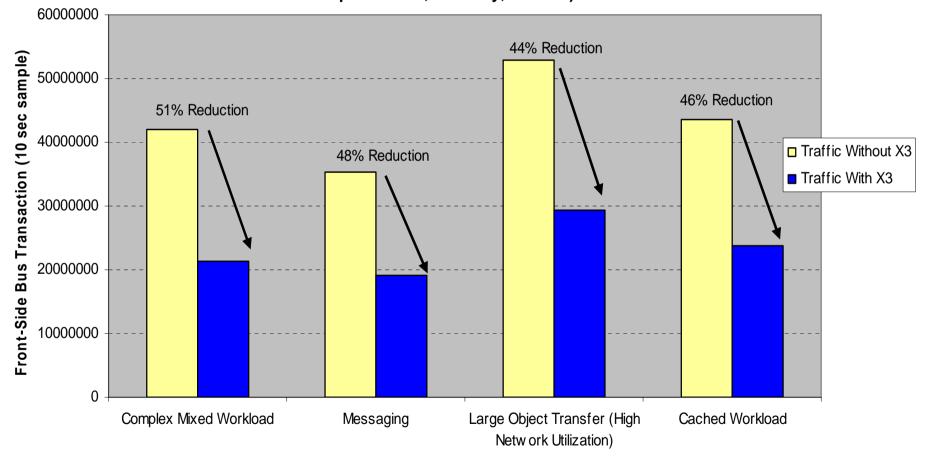


Reduction in FSB Traffic = Higher Performance

IBM X3 Architecture

System Traffic Reduction = Performance Increase

Performance increases achieved by reduction of traffic between system resources (such as processors, memory, and I/O)



Scenario



Intelligent Caching for Ultimate Performance

x366 & x260



Up to 4w: No L3 Needed XceL4v Intelligent Caching ■#1 4w Performance + Lower CPU Price = #1 Price Performance vs. HP & Dell





GHz

L2 L3

3.3GHz / 2M / 8M

3.0GHz / 2M / 8M 2.8GHz / 2M / 4M Up to 32w: L3 + XceL4v Above 4w, L3 combines with XceL4v to power #1 Raw Performance to 32w Unmatched x86-64 Scalability

x460 & MXE

Intel has introduced two variations of its next generation 64-bit Xeon MP

L2

3.66GHz / 1M

3.16GHz / 1M

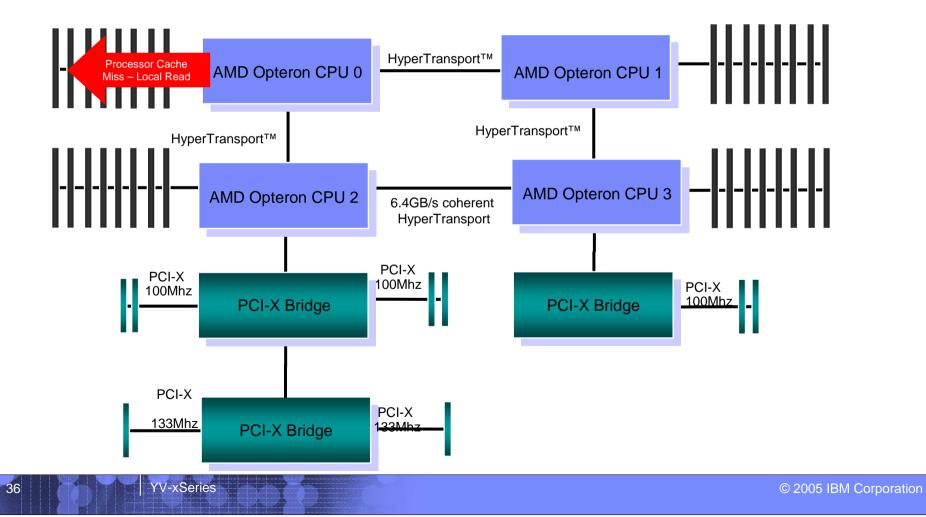
- Cranford: L2 only, Potomac: up to 8M L3
- XceL4v: 256MB of DD2-based virtual L4 cache per 4 CPUs (up to 2GB max)
 - Compare to 32MB per 4 CPUs in x440, 64MB in x445
- XceL4v[™] provides a performance boost to scalability powering #1 performance with 64-bit Intel Xeon MP with up to 8M L3 cache.
 - L3 is required only for scalability greater than 4-way



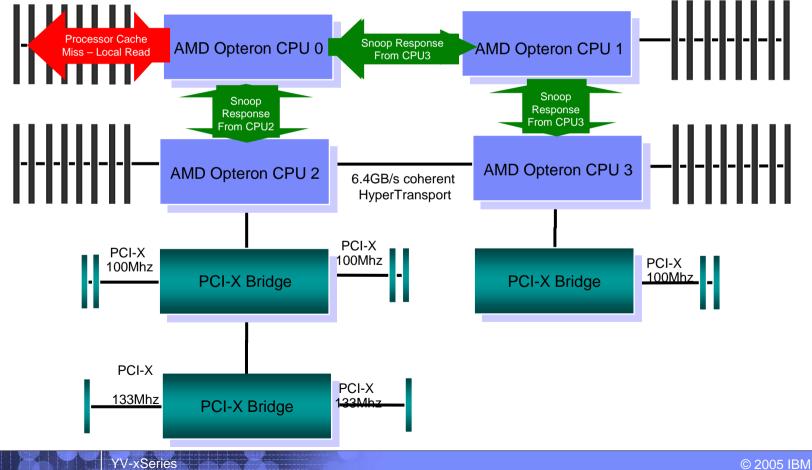
Intel Xeon vs AMD Opteron: fundamental differences



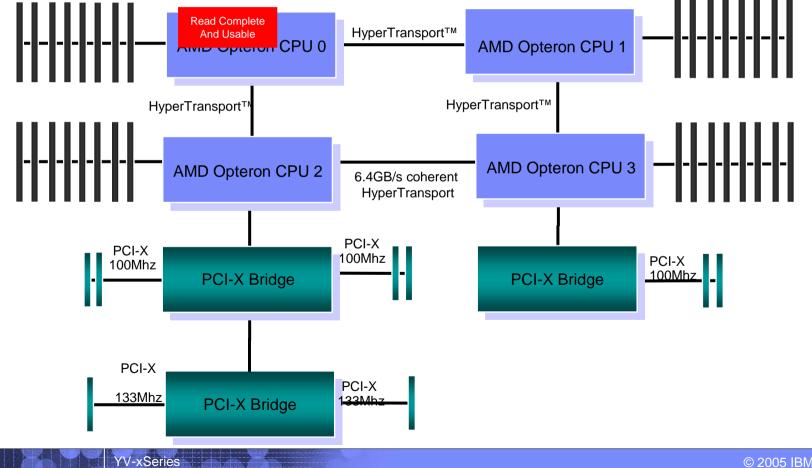
1. Local memory read happens fast - This low latency is well publicized



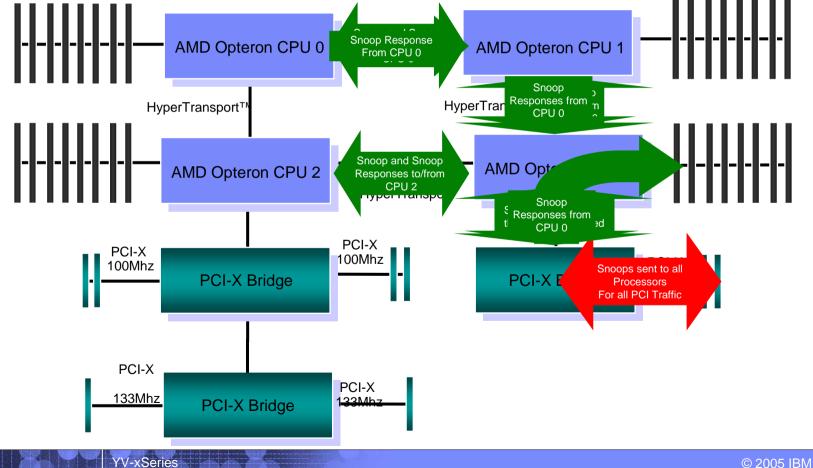
- 1. Local memory read happens fast This low latency is well publicized
- 2. But processor cannot use data until ALL snoops complete
- 3. In 4-way there are always two hops for snoops



- 1. Local memory read happens fast This low latency is well publicized
- 2. But processor cannot use data until snoop completes
- 3. In 4-way there are always two hops for snoops
- 4. CPU 3 is always the farthest away and determines minimum load to use time
- 5. Only now can data be used by processor



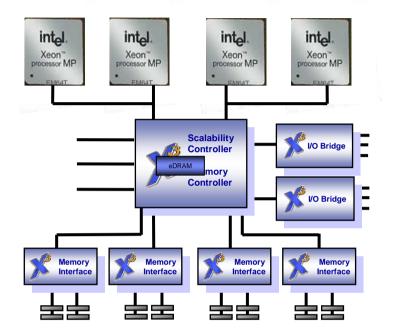
- 1. ALL PCI I/O also have to send snoops across the HT links to EVERY processor
- 2. The snoops must complete before PCI I/O can complete
- 3. As long as memory accesses are local and PCI traffic is local
 - 1. The HT Links are mostly used for snoop traffic
- 4. But for remote memory or I/O, snoops queue with remote traffic and performance suffers

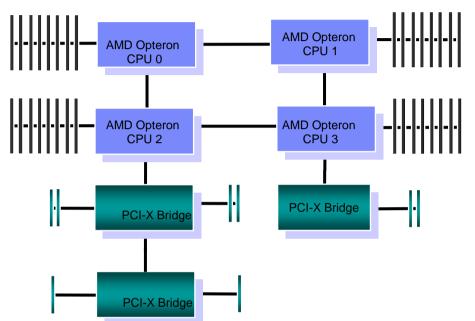


IBM eServer[®] X3 Architecture: Third-Generation Enterprise X-Architecture[™]



Xeon vs. Opteron – Fundamental Differences





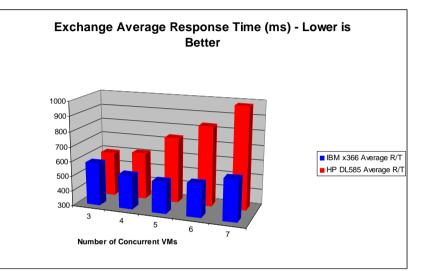
- Memory Bandwidth Performance
 - > Significant difference between memory architectures of Xeon and Opteron processors.
 - > Xeon processors uses a Front-Side Bus (FSB) that is shared among all processors connected to external memory controller.
 - Memory controller employs two channels to the actual DDR-II 400 (PC3200 DDR-II) memory DIMMs
 - > Opteron processors use embedded memory controller; all processors connected by HyperTransport Bus
 - Each processor has two channels to DDR-I memory (going EOL)
- Memory Latency Performance
 - > Similar for both processors with advantage depending upon NUMA awareness and access characteristics of workload
 - Multi-threaded, multi-user workloads cause highly random memory address activity causing frequent page faults
 - > Latency, not memory bandwidth, dominates performance because page-hits rarely occur



VeriTest.

New Test Results IBM vs. HP

- New report July, 2005
 - IBM commissioned study
 - > x366 vs. DL 585
 - Similarly priced systems
- Simulates real-world virtualized workloads driving 90% processor utilization (as opposed to AMD sponsored study)
- 41% faster response times for Exchange and SQL Server applications



Key findings

 In a 'real world' mixed application virtualized environment (including Terminal Services, two file and print, static and dynamic WEB, Collaboration and Database applications, all running simultaneously), VeriTest found that the IBM x366 Intel® Xeon Processor MP based server, using X3 Architecture, out-performed a similarly configured and priced HP DL585 AMD Opteron based server on Exchange and SQL workloads, delivering response times that were over 41% faster.

http://www.veritest.com/clients/reports/ibm/IBM_eServer_X3_0705.pdf

IBM eServer[®] X3 Architecture: Third-Generation Enterprise X-Architecture[™]

